ABSTRACT

The present invention is a wafer-holding carrier 1 wherein the carrier has polishing agent-passing holes 3, 4 for passing the polishing agent through as well as wafer-holding holes 2 for containing and holding wafers, and the total area of the polishing agent-passing holes occupies 15% or more of a main surface of the carrier. Preferably, the total area of the polishing agent-passing holes occupies 30% or less of the main surface of the carrier, and each of the polishing agent-passing holes has a circular shape of a diameter of 5 mm - 30 mm, and the holes are arranged in the form of concentric circle or lattice on the carrier entirely. Thereby, there can be provided an art that even when performing polishing by using a hard polishing pad in a double-side polishing apparatus, particularly, a double-side polishing apparatus having a carrier moving circularly without rotation, it is not necessary to reform the apparatus largely, and the wafer of high flatness can be finished without a tapered shape, peripheral sag, and such.